

therefor:

B13 --As Figures 3 and 4 illustrate, the mold in which the substrate 1 is stamped may be shaped in such a way that the stamped substrate 1 exhibits, at the edge of the gutter 4, a protuberance 7 which constitutes the excess material to be displaced during the crimping; the height of this protuberance is adjusted so as to remain below the upper level of the electronics card 2, so as not to prevent the screen-printing of the soldering paste for mounting the components prior to the cover 3 being put in place.--

At page 4, please delete the sixth full paragraph commencing at line 34 and insert therefor:

B14 --Moreover, the depth of the gutter 4 is adjusted so that the bottom of the gutter 4 and the return 5 are below the electronics card 2. This makes it possible to prevent any risk of leakage of electromagnetic waves.--

IN THE CLAIMS

Please AMEND claims 4, 5, and 7 as follows:

B15 4. (Amended) A method of producing an assembly comprising a printed-circuit electronics card mounted on a metal substrate with a metal screening cover electrically connected to the substrate, the method comprising:

- forming a gutter on a metallic substrate by stamping;
- mounting a printed circuit onto a surface of the metallic substrate adjacent to the gutter;
- positioning a screening cover having an edge including a tab so that the tab rests substantially within the gutter;
- crimping the edge of the screening cover onto the substrate, whereby the cover